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REVISION HISTORY

11/2017—Rev. A to Rev. B

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7/2011—Rev. 0 to Rev. A

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7/2010—Revision 0: Initial Version

SPECIFICATIONS

±15 V DUAL SUPPLY

$V_{DD} = 15\text{ V} \pm 10\%$, $V_{SS} = -15\text{ V} \pm 10\%$, GND = 0 V, unless otherwise noted.

Table 1.

Parameter	25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V _{DD} to V _{SS}	V	V _S = ±10 V, I _S = −10 mA; see Figure 23 V _{DD} = +13.5 V, V _{SS} = −13.5 V V _S = ±10 V, I _S = −10 mA
On Resistance, R _{ON}	9.8	14	16	Ω typ	
	11			Ω max	
On-Resistance Match Between Channels, ΔR _{ON}	0.35			Ω typ	
	0.7	0.9	1.1	Ω max	V _S = ±10 V, I _S = −10 mA
On-Resistance Flatness, R _{FLAT(ON)}	1.2			Ω typ	
	1.6	2	2.2	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I _S (Off)	±0.05	±0.75	±6	nA typ	V _{DD} = +16.5 V, V _{SS} = −16.5 V V _S = V _S = ±10 V, V _D = ∓10 V; see Figure 24
	±0.25			nA max	
Drain Off Leakage, I _D (Off)	±0.1	±2	±16	nA typ	V _S = V _S = ±10 V, V _D = ∓10 V; see Figure 24
	±0.4			nA max	
Channel On Leakage, I _D , I _S (On)	±0.1	±2	±16	nA typ	V _S = V _D = ±10 V; see Figure 25
	±0.4			nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}	0.002		2.0	V min	V _{IN} = V _{GND} or V _{DD}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}			±0.1	μA typ	
				μA max	
Digital Input Capacitance, C _{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS ¹					
Transition Time, t _{TRANSITION}	187	285	330	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = 10 V; see Figure 30
	242			ns max	
t _{ON} (EN)	160	247	278	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = 10 V; see Figure 32
	204			ns max	
t _{OFF} (EN)	125	168	183	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = 10 V; see Figure 32
	145			ns max	
Break-Before-Make Time Delay, t _o	45		12	ns typ	R _L = 300 Ω, C _L = 35 pF V _{S1} = V _{S2} = 10 V; see Figure 31
				ns min	
Charge Injection, Q _{INJ}	220			pC typ	V _S = 0 V, R _S = 0 Ω, C _L = 1 nF; see Figure 33
Off Isolation	−78			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 100 kHz; see Figure 26
Channel-to-Channel Crosstalk	−58			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 28
Total Harmonic Distortion + Noise	0.009			% typ	R _L = 1 k Ω, 15 V p-p, f = 20 Hz to 20 kHz; see Figure 29
−3 dB Bandwidth	53			MHz typ	R _L = 50 Ω, C _L = 5 pF; see Figure 27
Insertion Loss	−0.7			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 27
C _S (Off)	19			pF typ	V _S = 0 V, f = 1 MHz
C _D (Off)	92			pF typ	V _S = 0 V, f = 1 MHz
C _D , C _S (On)	132			pF typ	V _S = 0 V, f = 1 MHz
POWER REQUIREMENTS					
I _{DD}	45		70	μA typ	V _{DD} = +16.5 V, V _{SS} = −16.5 V Digital inputs = 0 V or V _{DD}
	55			μA max	
I _{SS}	0.001		1	μA typ	Digital inputs = 0 V or V _{DD}
			±9/±22	μA max	
V _{DD} /V _{SS}				V min/max	GND = 0 V

¹ Guaranteed by design; not subject to production test.

±20 V DUAL SUPPLY

$V_{DD} = 20\text{ V} \pm 10\%$, $V_{SS} = -20\text{ V} \pm 10\%$, GND = 0 V, unless otherwise noted.

Table 2.

Parameter	25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V _{DD} to V _{SS}	V	V _S = ±15 V, I _S = −10 mA; see Figure 23 V _{DD} = +18 V, V _{SS} = −18 V V _S = ±15 V, I _S = −10 mA
On Resistance, R _{ON}	9	13	15	Ω typ	
	10			Ω max	
On-Resistance Match Between Channels, ΔR _{ON}	0.35			Ω typ	
	0.7	0.9	1.1	Ω max	
On-Resistance Flatness, R _{FLAT(ON)}	1.5			Ω typ	
	1.8	2.2	2.5	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I _S (Off)	±0.05	±0.75	±6	nA typ	V _{DD} = +22 V, V _{SS} = −22 V
	±0.25			nA max	V _S = ±15 V, V _D = ∓15 V; see Figure 24
Drain Off Leakage, I _D (Off)	±0.1			nA typ	V _S = ±15 V, V _D = ∓15 V; see Figure 24
	±0.4	±2	±16	nA max	V _S = V _D = ±15 V; see Figure 25
Channel On Leakage, I _D , I _S (On)	±0.1			nA typ	
	±0.4	±2	±16	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}	0.002		2.0	V min	V _{IN} = V _{GND} or V _{DD}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}			±0.1	μA typ	
				μA max	
Digital Input Capacitance, C _{IN}	5		pF typ		
DYNAMIC CHARACTERISTICS ¹					
Transition Time, t _{TRANSITION}	175	262	301	ns typ	R _L = 300 Ω, C _L = 35 pF
	224			ns max	V _S = +10 V; see Figure 30
t _{ON} (EN)	148			ns typ	R _L = 300 Ω, C _L = 35 pF
	185	222	250	ns max	V _S = 10 V; see Figure 32
t _{OFF} (EN)	120	159	173	ns typ	R _L = 300 Ω, C _L = 35 pF
	142			ns max	V _S = 10 V; see Figure 32
Break-Before-Make Time Delay, t _D	40			ns typ	R _L = 300 Ω, C _L = 35 pF
			10	ns min	V _{S1} = V _{S2} = 10 V; see Figure 31
Charge Injection, Q _{INJ}	290			pC typ	V _S = 0 V, R _S = 0 Ω, C _L = 1 nF; see Figure 33
Off Isolation	−78			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 100 kHz; see Figure 26
Channel-to-Channel Crosstalk	−58			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 28
Total Harmonic Distortion + Noise	0.008			% typ	R _L = 1 kΩ, 20 V p-p, f = 20 Hz to 20 kHz; see Figure 29
−3 dB Bandwidth	54			MHz typ	R _L = 50 Ω, C _L = 5 pF; see Figure 27
Insertion Loss	−0.6			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 27
C _S (Off)	18			pF typ	V _S = 0 V, f = 1 MHz
C _D (Off)	88			pF typ	V _S = 0 V, f = 1 MHz
C _D , C _S (On)	129			pF typ	V _S = 0 V, f = 1 MHz
POWER REQUIREMENTS					
I _{DD}	50		110	μA typ	V _{DD} = +22 V, V _{SS} = −22 V
	70			μA max	Digital inputs = 0 V or V _{DD}
I _{SS}	0.001			μA typ	Digital inputs = 0 V or V _{DD}
			1	μA max	
V _{DD} /V _{SS}			±9/±22	V min/max	GND = 0 V

¹ Guaranteed by design; not subject to production test.

+12 V SINGLE SUPPLY

$V_{DD} = 12\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.

Table 3.

Parameter	25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	V _S = 0 V to 10 V, I _S = −10 mA; see Figure 23 V _{DD} = 10.8 V, V _{SS} = 0 V
On Resistance, R _{ON}	19	27	31	Ω typ	
	22			Ω max	
On-Resistance Match Between Channels, ΔR _{ON}	0.4			Ω typ	
	0.8	1	1.2	Ω max	V _S = 0 V to 10 V, I _S = −10 mA
On-Resistance Flatness, R _{FLAT(ON)}	4.4			Ω typ	
	5.5	6.5	7.5	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I _S (Off)	±0.02	±0.75	±6	nA typ	V _{DD} = 13.2 V, V _{SS} = 0 V V _S = 1 V/10 V, V _D = 10 V/1 V; see Figure 24
	±0.25			nA max	
Drain Off Leakage, I _D (Off)	±0.05	±2	±16	nA typ	V _S = 1 V/10 V, V _D = 10 V/1 V; see Figure 24
	±0.4			nA max	
Channel On Leakage, I _D , I _S (On)	±0.05			nA typ	
	±0.4	±2	±16	nA max	V _S = V _D = 1 V/10 V; see Figure 25
DIGITAL INPUTS					
Input High Voltage, V _{INH}	0.002		2.0	V min	V _{IN} = V _{GND} or V _{DD}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}			±0.1	μA typ	
				μA max	
Digital Input Capacitance, C _{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS ¹					
Transition Time, t _{TRANSITION}	266	446	515	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = +8 V; see Figure 30
	358			ns max	
t _{ON} (EN)	260	423	485	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = 8 V; see Figure 32
	339			ns max	
t _{OFF} (EN)	135	189	210	ns typ	R _L = 300 Ω, C _L = 35 pF V _S = 8 V; see Figure 32
	162			ns max	
Break-Before-Make Time Delay, t _D	125		45	ns typ	R _L = 300 Ω, C _L = 35 pF V _{S1} = V _{S2} = 8 V; see Figure 31
				ns min	
Charge Injection, Q _{INJ}	92			pC typ	V _S = 6 V, R _S = 0 Ω, C _L = 1 nF; see Figure 33
Off Isolation	−78			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 26
Channel-to-Channel Crosstalk	−58			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 28
Total Harmonic Distortion + Noise	0.075			% typ	R _L = 1 k Ω, 6 V p-p, f = 20 Hz to 20 kHz; see Figure 29
−3 dB Bandwidth	43			MHz typ	R _L = 50 Ω, C _L = 5 pF; see Figure 27
Insertion Loss	−1.36			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 27
C _S (Off)	22			pF typ	V _S = 6 V, f = 1 MHz
C _D (Off)	105			pF typ	V _S = 6 V, f = 1 MHz
C _D , C _S (On)	140			pF typ	V _S = 6 V, f = 1 MHz
POWER REQUIREMENTS					
I _{DD}	40		65	μA typ	V _{DD} = 13.2 V Digital inputs = 0 V or V _{DD}
	50			μA max	
V _{DD}			9/40	V min/max	GND = 0 V, V _{SS} = 0 V

¹ Guaranteed by design; not subject to production test.

+36 V SINGLE SUPPLY

$V_{DD} = 36\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.

Table 4.

Parameter	25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance, R_{ON}	10.6 12	15	17	Ω typ Ω max	$V_S = 0\text{ V to }30\text{ V}$, $I_S = -10\text{ mA}$; see Figure 23 $V_{DD} = 32.4\text{ V}$, $V_{SS} = 0\text{ V}$
On-Resistance Match Between Channels, ΔR_{ON}	0.35			Ω typ	$V_S = 0\text{ V to }30\text{ V}$, $I_S = -10\text{ mA}$
On-Resistance Flatness, $R_{FLAT(ON)}$	0.7 2.7 3.2	0.9 3.8	1.1 4.5	Ω max Ω typ Ω max	$V_S = 0\text{ V to }30\text{ V}$, $I_S = -10\text{ mA}$
LEAKAGE CURRENTS					$V_{DD} = 39.6\text{ V}$, $V_{SS} = 0\text{ V}$
Source Off Leakage, I_S (Off)	± 0.05 ± 0.25	± 0.75	± 6	nA typ nA max	$V_S = 1\text{ V/30 V}$, $V_D = 30\text{ V/1 V}$; see Figure 24
Drain Off Leakage, I_D (Off)	± 0.1 ± 0.4	± 2	± 16	nA typ nA max	$V_S = 1\text{ V/30 V}$, $V_D = 30\text{ V/1 V}$; see Figure 24
Channel On Leakage, I_D , I_S (On)	± 0.1 ± 0.4	± 2	± 16	nA typ nA max	$V_S = V_D = 1\text{ V/30 V}$; see Figure 25
DIGITAL INPUTS					
Input High Voltage, V_{INH}			2.0	V min	
Input Low Voltage, V_{INL}			0.8	V max	
Input Current, I_{INL} or I_{INH}	0.002		± 0.1	μA typ μA max	$V_{IN} = V_{GND}$ or V_{DD}
Digital Input Capacitance, C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS¹					
Transition Time, $t_{TRANSITION}$	196 256	276	314	ns typ ns max	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 18\text{ V}$; see Figure 30
t_{ON} (EN)	170 214	247	273	ns typ ns max	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 18\text{ V}$; see Figure 32
t_{OFF} (EN)	130 172	167	176	ns typ ns max	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 18\text{ V}$; see Figure 32
Break-Before-Make Time Delay, t_D	52		13	ns typ ns min	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_{S1} = V_{S2} = 18\text{ V}$; see Figure 31
Charge Injection, Q_{INJ}	280			pC typ	$V_S = 18\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\text{ nF}$; see Figure 33
Off Isolation	−78			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 26
Channel-to-Channel Crosstalk	−58			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 28
Total Harmonic Distortion + Noise	0.03			% typ	$R_L = 1\text{ k}\Omega$, 18 V p-p , $f = 20\text{ Hz to }20\text{ kHz}$; see Figure 29
−3 dB Bandwidth	47			MHz typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$; see Figure 27
Insertion Loss	−0.85			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 27
C_S (Off)	18			pF typ	$V_S = 18\text{ V}$, $f = 1\text{ MHz}$
C_D (Off)	89			pF typ	$V_S = 18\text{ V}$, $f = 1\text{ MHz}$
C_D , C_S (On)	128			pF typ	$V_S = 18\text{ V}$, $f = 1\text{ MHz}$
POWER REQUIREMENTS					$V_{DD} = 39.6\text{ V}$
I_{DD}	80 100		130 9/40	μA typ μA max V min/max	Digital inputs = 0 V or V_{DD} $GND = 0\text{ V}$, $V_{SS} = 0\text{ V}$

¹ Guaranteed by design; not subject to production test.

CONTINUOUS CURRENT PER CHANNEL, S OR D

Table 5.

Parameter	25°C	85°C	125°C	Unit
CONTINUOUS CURRENT, S OR D				
$V_{DD} = +15\text{ V}$, $V_{SS} = -15\text{ V}$				
TSSOP ($\theta_{JA} = 112.6^{\circ}\text{C/W}$)	165	96	49	mA max
LFCSP ($\theta_{JA} = 30.4^{\circ}\text{C/W}$)	290	141	57	mA max
$V_{DD} = +20\text{ V}$, $V_{SS} = -20\text{ V}$				
TSSOP ($\theta_{JA} = 112.6^{\circ}\text{C/W}$)	176	101	51	mA max
LFCSP ($\theta_{JA} = 30.4^{\circ}\text{C/W}$)	282	146	58	mA max
$V_{DD} = 12\text{ V}$, $V_{SS} = 0\text{ V}$				
TSSOP ($\theta_{JA} = 112.6^{\circ}\text{C/W}$)	114	72	42	mA max
LFCSP ($\theta_{JA} = 30.4^{\circ}\text{C/W}$)	203	112	53	mA max
$V_{DD} = 36\text{ V}$, $V_{SS} = 0\text{ V}$				
TSSOP ($\theta_{JA} = 112.6^{\circ}\text{C/W}$)	149	89	48	mA max
LFCSP ($\theta_{JA} = 30.4^{\circ}\text{C/W}$)	263	133	56	mA max

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 6.

Parameter	Rating
V_{DD} to V_{SS}	48 V
V_{DD} to GND	−0.3 V to +48 V
V_{SS} to GND	+0.3 V to −48 V
Analog Inputs ¹	$V_{SS} - 0.3\text{ V}$ to $V_{DD} + 0.3\text{ V}$ or 30 mA, whichever occurs first
Digital Inputs ¹	$V_{SS} - 0.3\text{ V}$ to $V_{DD} + 0.3\text{ V}$ or 30 mA, whichever occurs first
Peak Current, Sx or D Pins	515 mA (pulsed at 1 ms, 10% duty cycle maximum)
Continuous Current, S or D ²	Data + 15%
Operating Temperature Range	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
Thermal Impedance, θ_{JA}	
16-Lead TSSOP, θ_{JA} Thermal Impedance (4-Layer Board)	112.6°C/W
16-Lead LFCSP, θ_{JA} Thermal Impedance (4-Layer Board)	30.4°C/W
Reflow Soldering Peak Temperature, Pb Free	260(+0/−5)°C

¹ Overvoltages at the Sx and D pins are clamped by internal diodes. Limit current to the maximum ratings given.

² See Table 5.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

Only one absolute maximum rating can be applied at any one time.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

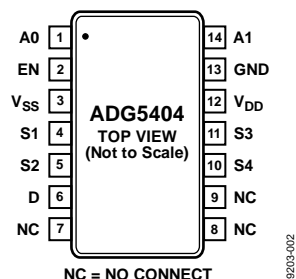
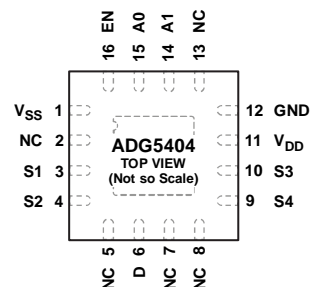


Figure 2. TSSOP Pin Configuration



NOTES

1. NC = NO CONNECT.
2. EXPOSED PAD TIED TO SUBSTRATE, V_{SS} .

Figure 3. LFCSP Pin Configuration

Table 7. Pin Function Descriptions

Pin No.		Mnemonic	Description
TSSOP	LFCSP		
1	15	A0	Logic Control Input.
2	16	EN	Active High Digital Input. When this pin is low, the device is disabled and all switches are off. When this pin is high, the Ax logic inputs determine the on switches.
3	1	V_{SS}	Most Negative Power Supply Potential.
4	3	S1	Source Terminal. Can be an input or an output.
5	4	S2	Source Terminal. Can be an input or an output.
6	6	D	Drain Terminal. Can be an input or an output.
7 to 9	2, 5, 7, 8, 13	NC	No Connection.
10	9	S4	Source Terminal. Can be an input or an output.
11	10	S3	Source Terminal. Can be an input or an output.
12	11	V_{DD}	Most Positive Power Supply Potential.
13	12	GND	Ground (0 V) Reference.
14	14	A1	Logic Control Input.
	EP	Exposed Pad	The exposed pad is connected internally. For increased reliability of the solder joints and maximum thermal capability, it is recommended that the pad be soldered to the substrate, V_{SS} .

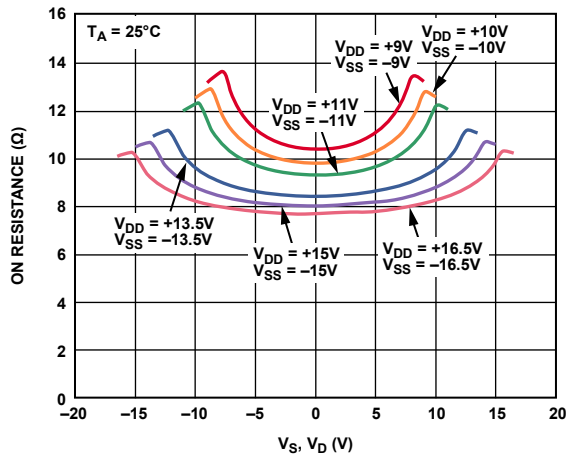
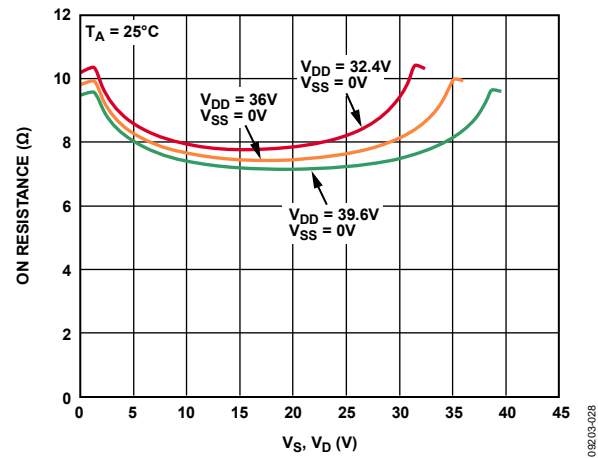
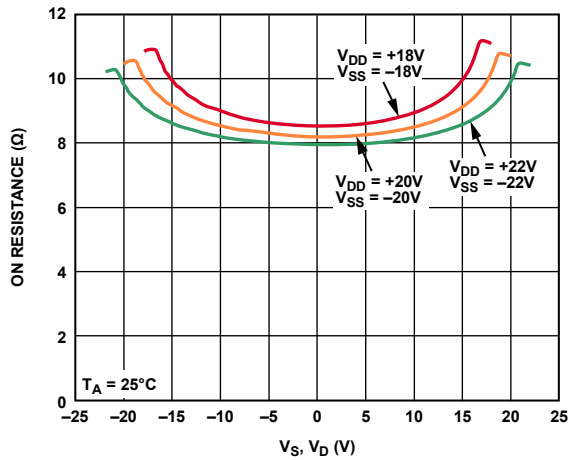
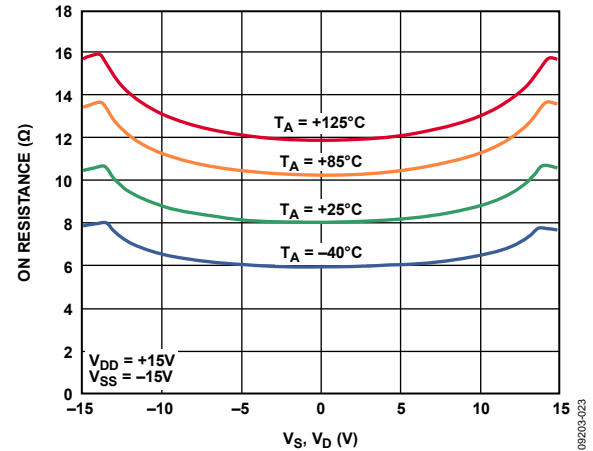
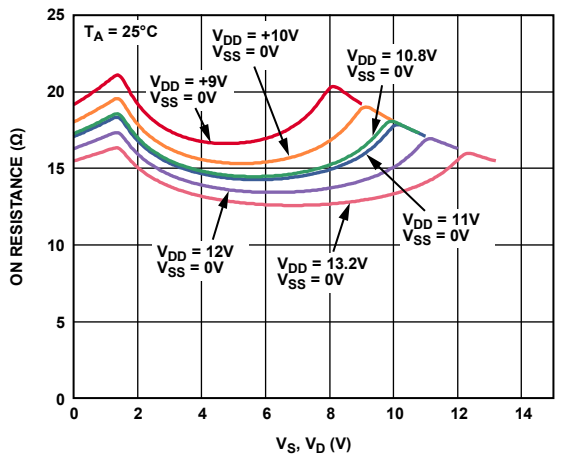
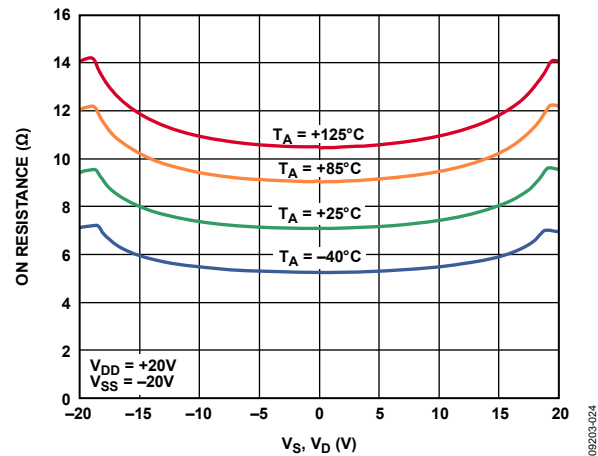
TRUTH TABLE

Table 8.

EN	A1	A0	S1	S2	S3	S4
0	X ¹	X ¹	Off	Off	Off	Off
1	0	0	On	Off	Off	Off
1	0	1	Off	On	Off	Off
1	1	0	Off	Off	On	Off
1	1	1	Off	Off	Off	On

¹ X = don't care.

TYPICAL PERFORMANCE CHARACTERISTICS

Figure 4. R_{ON} as a Function of V_D (V_S), Dual SupplyFigure 7. R_{ON} as a Function of V_D (V_S), Single SupplyFigure 5. R_{ON} as a Function of V_D (V_S), Dual SupplyFigure 8. R_{ON} as a Function of V_D (V_S) for Different Temperatures, ± 15 V Dual SupplyFigure 6. R_{ON} as a Function of V_D (V_S), Single SupplyFigure 9. R_{ON} as a Function of V_D (V_S) for Different Temperatures, ± 20 V Dual Supply

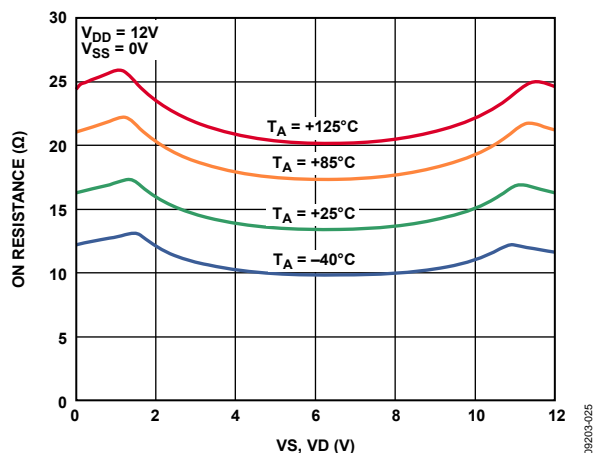


Figure 10. R_{ON} as a Function of V_D (V_S) for Different Temperatures, 12 V Single Supply

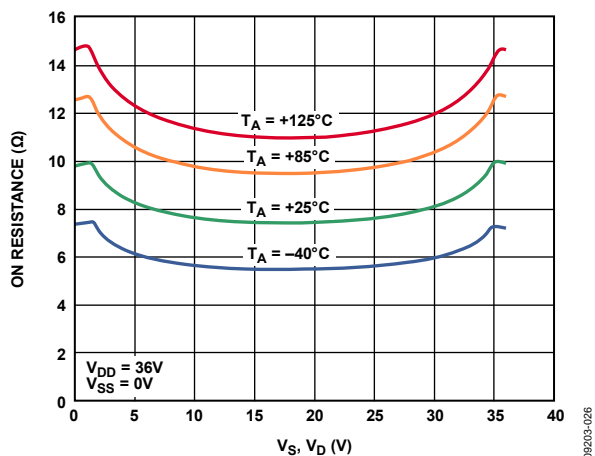


Figure 11. R_{ON} as a Function of V_D (V_S) for Different Temperatures, 36 V Single Supply

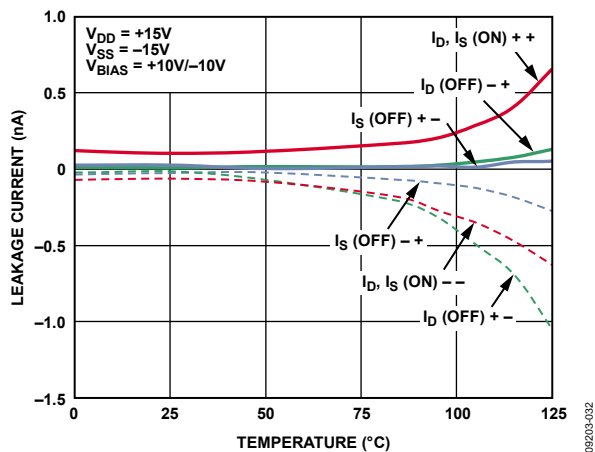


Figure 12. Leakage Currents vs. Temperature, ± 15 V Dual Supply

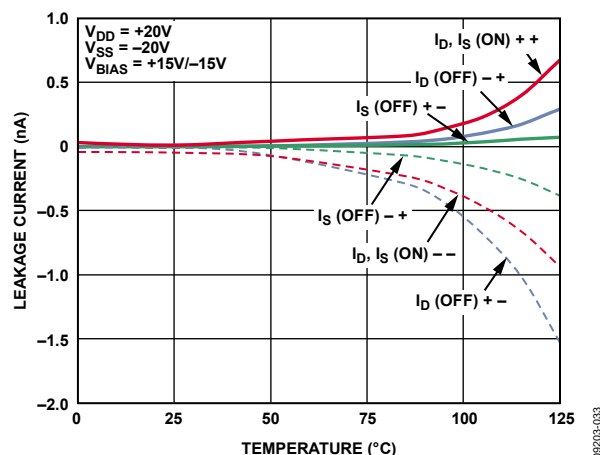


Figure 13. Leakage Currents vs. Temperature, ± 20 V Dual Supply

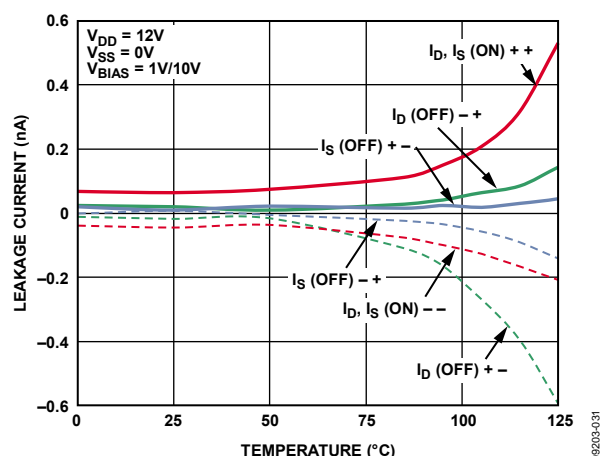


Figure 14. Leakage Currents vs. Temperature, 12 V Single Supply

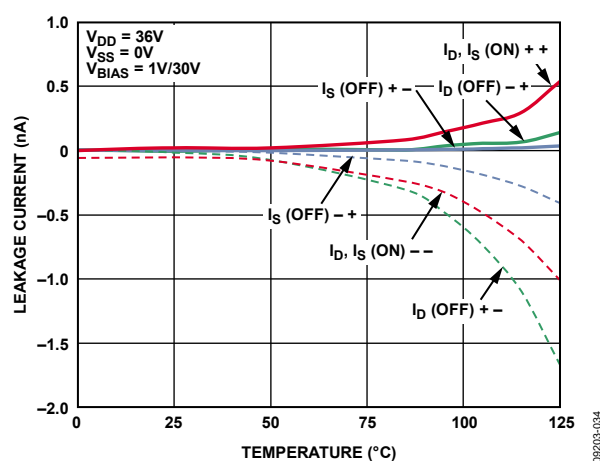


Figure 15. Leakage Currents vs. Temperature, 36 V Single Supply

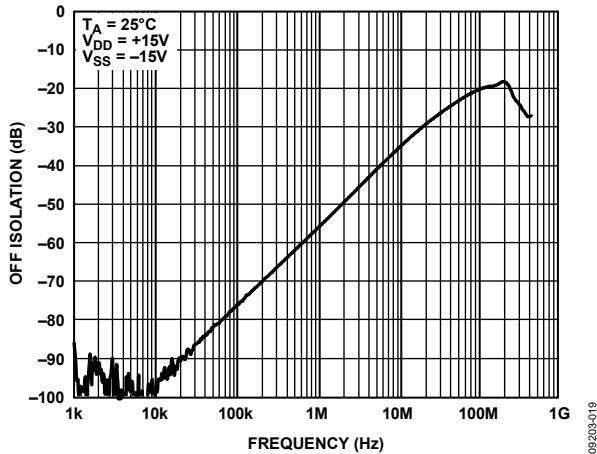


Figure 16. Off Isolation vs. Frequency, ± 15 V Dual Supply

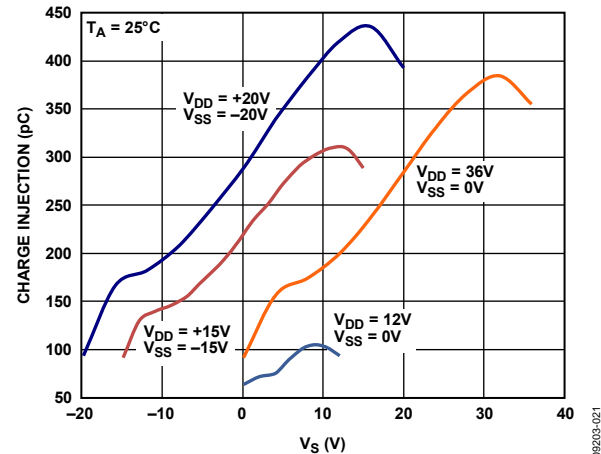


Figure 19. Charge Injection vs. Source Voltage

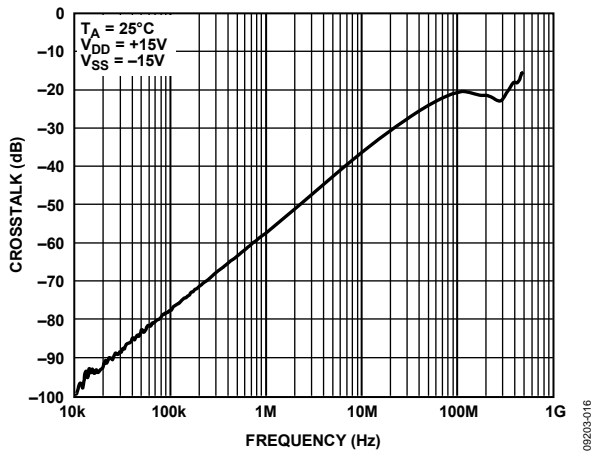


Figure 17. Crosstalk vs. Frequency, ± 15 V Dual Supply

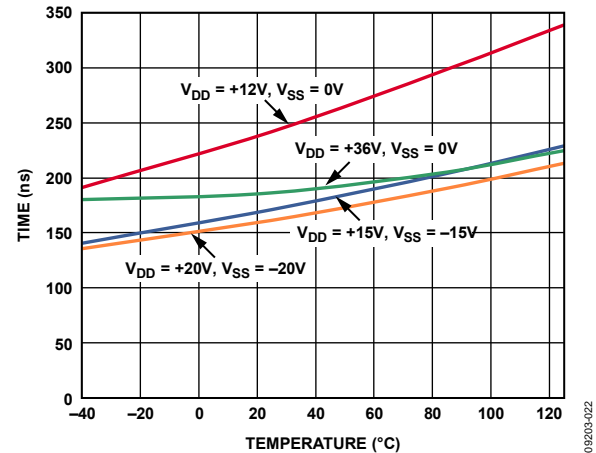


Figure 20. Transition Time vs. Temperature

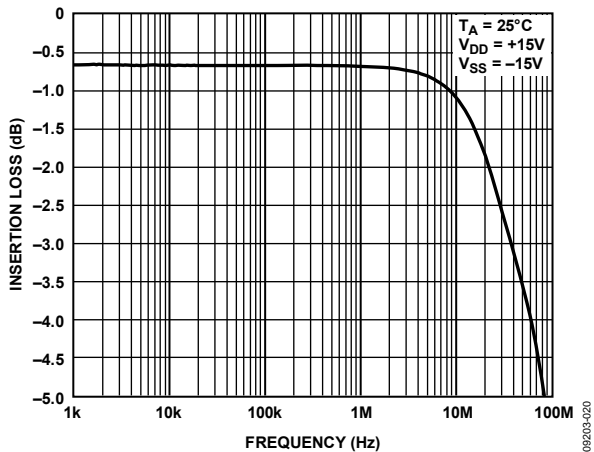


Figure 18. On Response vs. Frequency, ± 15 V Dual Supply

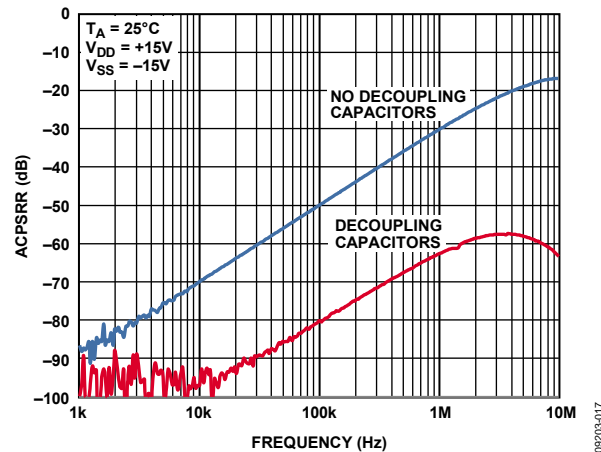


Figure 21. ACPSRR vs. Frequency, ± 15 V Dual Supply

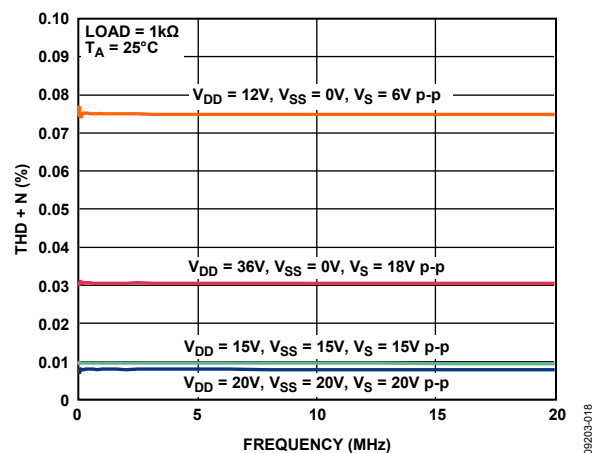


Figure 22. THD + N vs. Frequency, $\pm 15\text{V}$ Dual Supply

TEST CIRCUITS

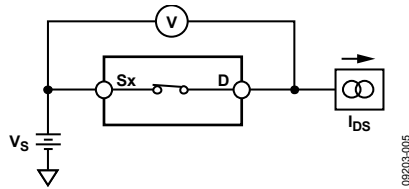


Figure 23. On Resistance

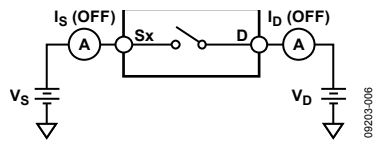


Figure 24. Off Leakage

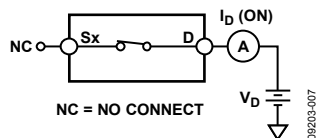


Figure 25. On Leakage

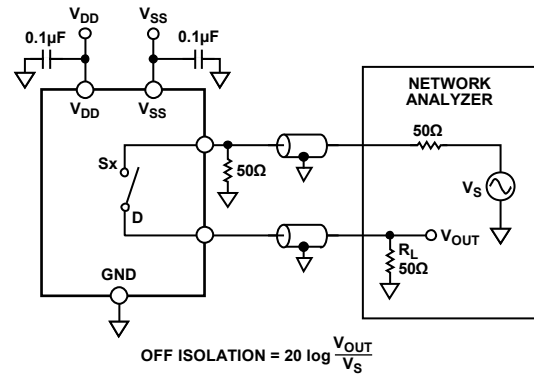


Figure 26. Off Isolation

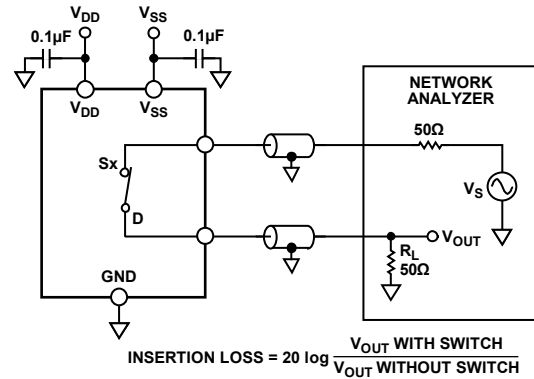


Figure 27. Bandwidth

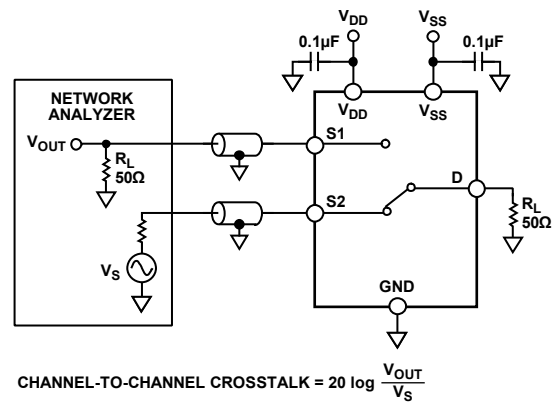


Figure 28. Channel-to-Channel Crosstalk

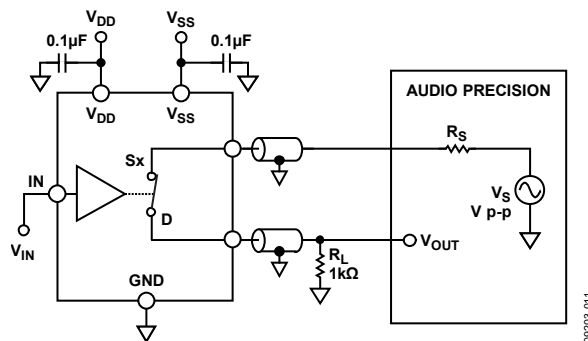


Figure 29. THD + Noise

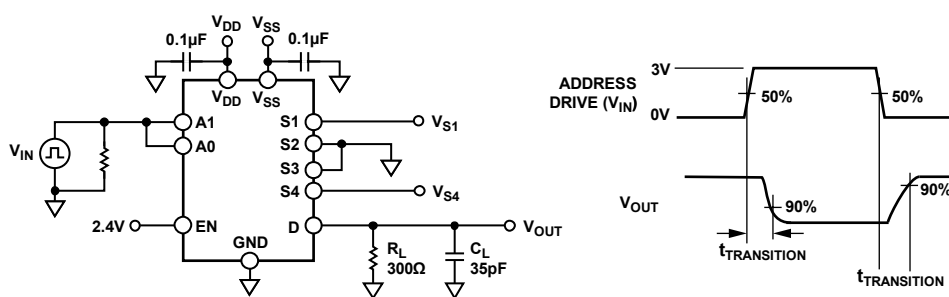


Figure 30. Address to Output Switching Times

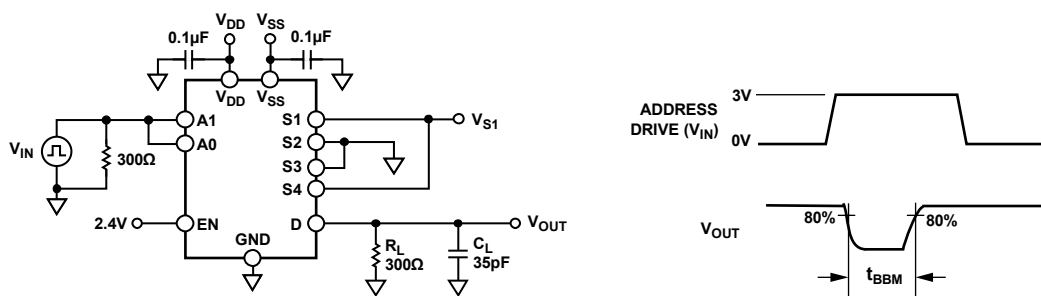


Figure 31. Break-Before-Make Time Delay



Figure 32. Enable-to-Output Switching Delay



Figure 33. Charge Injection

TERMINOLOGY

I_{DD}

The positive supply current.

I_{SS}

The negative supply current.

V_D (V_S)

The analog voltage on Terminal D and Terminal S.

R_{ON}

The ohmic resistance between Terminal D and Terminal S.

R_{FLAT(ON)}

Flatness that is defined as the difference between the maximum and minimum value of on resistance measured over the specified analog signal range.

I_S (Off)

The source leakage current with the switch off.

I_D (Off)

The drain leakage current with the switch off.

I_D, I_S (On)

The channel leakage current with the switch on.

V_{INL}

The maximum input voltage for Logic 0.

V_{INH}

The minimum input voltage for Logic 1.

I_{INL} (I_{INH})

The input current of the digital input.

C_S (Off)

The off switch source capacitance, which is measured with reference to ground.

C_D (Off)

The off switch drain capacitance, which is measured with reference to ground.

C_D, C_S (On)

The on switch capacitance, which is measured with reference to ground.

C_{IN}

The digital input capacitance.

t_{TRANSITION}

The delay time between the 50% and 90% points of the digital input and switch-on condition when switching from one address state to another.

t_{ON} (EN)

The delay between applying the digital control input and the output switching on. See Figure 32.

t_{OFF} (EN)

The delay between applying the digital control input and the output switching off.

Charge Injection

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

Off Isolation

A measure of unwanted signal coupling through an off switch.

Crosstalk

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

Bandwidth

The frequency at which the output is attenuated by 3 dB.

On Response

The frequency response of the on switch.

Insertion Loss

The loss due to the on resistance of the switch.

THD + N

The ratio of the harmonic amplitude plus noise of the signal to the fundamental.

ACPSRR (AC Power Supply Rejection Ratio)

The ratio of the amplitude of signal on the output to the amplitude of the modulation. This is a measure of the part's ability to avoid coupling noise and spurious signals that appear on the supply voltage pin to the output of the switch. The dc voltage on the device is modulated by a sine wave of 0.62 V p-p.

TRENCH ISOLATION

In the ADG5404, an insulating oxide layer (trench) is placed between the NMOS and the PMOS transistors of each CMOS switch. Parasitic junctions, which occur between the transistors in junction-isolated switches, are eliminated, and the result is a completely latch-up proof switch.

In junction isolation, the N and P wells of the PMOS and NMOS transistors form a diode that is reverse-biased under normal operation. However, during overvoltage conditions, this diode can become forward-biased. A silicon-controlled rectifier (SCR) type circuit is formed by the two transistors, causing a significant amplification of the current that, in turn, leads to latch-up. With trench isolation, this diode is removed, and the result is a latch-up proof switch.

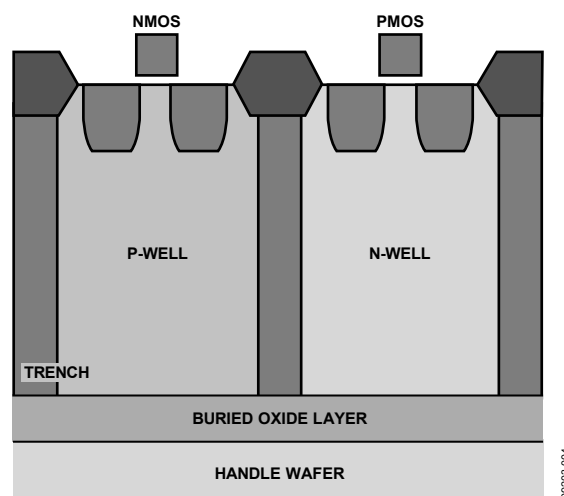


Figure 34. Trench Isolation

APPLICATIONS INFORMATION

The ADG54xx family of switches and multiplexers provide a robust solution for instrumentation, industrial, automotive, aerospace, and other harsh environments that are prone to latch-up, which is an undesirable high current state that can lead to device failure and persists until the power supply is turned off. The ADG5404 high voltage multiplexer allows

single-supply operation from 9 V to 40 V and dual-supply operation from ± 9 V to ± 22 V. The ADG5404, as well as three other ADG54xx family members, [ADG5412/ADG5413](#) and [ADG5436](#), achieve an 8 kV human body model ESD rating that provides a robust solution and eliminates the need for separate protection circuitry designs in some applications.

OUTLINE DIMENSIONS

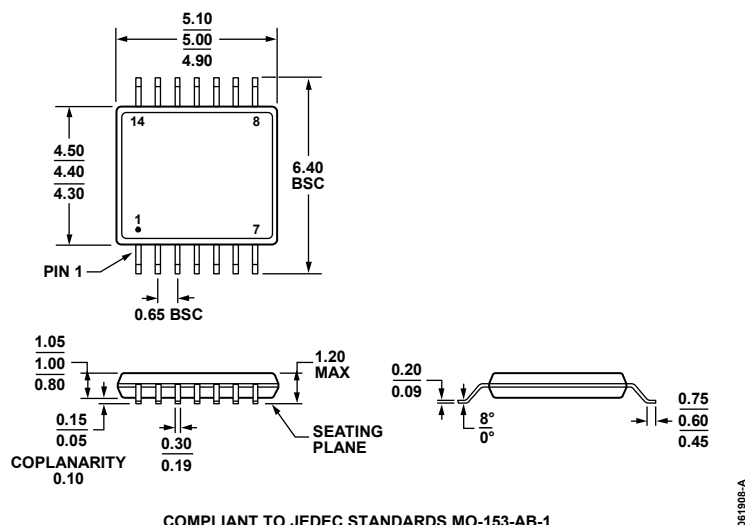


Figure 35. 14-Lead Thin Shrink Small Outline Package [TSSOP]
(RU-14)
Dimensions shown in millimeters

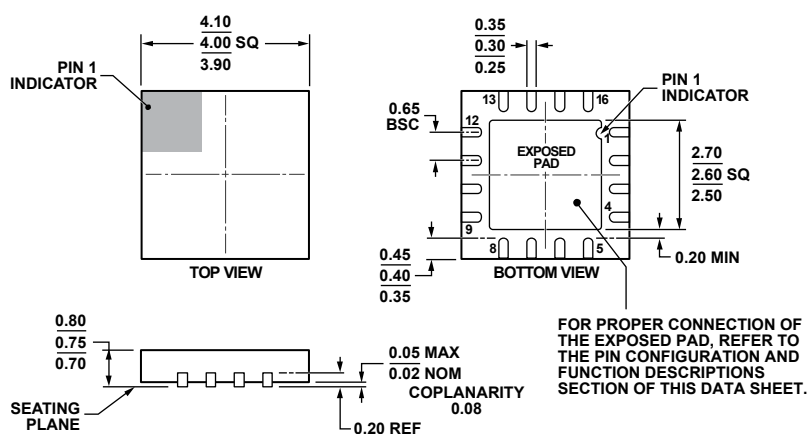


Figure 36. 16-Lead Lead Frame Chip Scale Package [LFCSP]
4 mm × 4 mm Body and 0.75 mm Package Height
(CP-16-17)
Dimensions shown in millimeters

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
ADG5404BRUZ	−40°C to +125°C	14-Lead Thin Shrink Small Outline Package [TSSOP]	RU-14
ADG5404BRUZ-REEL7	−40°C to +125°C	14-Lead Thin Shrink Small Outline Package [TSSOP]	RU-14
ADG5404BCPZ-REEL7	−40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP]	CP-16-17

¹ Z = RoHS Compliant Part.